IN THE CLAIMS:

Please amend the claims as follows:

Claims 1-10. (Canceled)

11. (Previously presented) An apparatus comprising:

a circuit board including

a substrate having a first surface and a second surface parallel to the first surface,

a set of electrical traces parallel to the first surface and the second surface,

a plurality of tapered through holes in the substrate from the first surface to the second surface, and

an electrically conductive elastomer filling each of the through holes, at least one of the electrical traces being in electrical contact with the electrically conductive elastomer in at least one of the through holes; and

an electronic component coupled to the circuit board, the electronic component having a plurality of electrical contacts, each in physical and electrical contact with the elastomer in a separate one of the through holes.

12. (Canceled)

13. (Original) An apparatus as recited in claim 11, wherein the electrical contacts are solder balls, each of the solder balls compressing the elastomer in a separate on of the through holes.

- 14. (Original) An apparatus as recited in claim 13, further comprising a fastener to secure the electronic component to the circuit board.
- 15. (Original) An apparatus as recited in claim 11, wherein the elastomer includes conductive particles interspersed therein.

Claims 16-31. (Canceled).

- 32. (Previously presented) An apparatus as recited in claim 11, wherein the circuit board includes an internal trace within the substrate, wherein the internal trace is in electrical contact with the electrically conductive elastomer in at least one of the through holes at a location within the substrate.
- 33. (Previously presented) An apparatus as recited in claim 32, wherein each of said at least one of the through holes is defined by a separate surface of the substrate, wherein a conductive layer is disposed on said surface in each of said at least one of the through holes, and wherein the internal trace is in electrical contact with the conductive layer in each of said at least one of the through holes.
- 34. (Previously presented) An apparatus as recited in claim 11, wherein the electronic component is coupled directly to the circuit board.